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1. Name of conveying party(ies):	2. Name and address of receiving party(ies)
Chi-Wen Liu Jung-Chih Tsao	Name: <u>Taiwan Semiconductor Manufacturing Company, Ltd.</u>
Shih-Tzung Chang Ying-Lang Wang Kei-Wei Chen	Internal Address:
Additional name(s) of conveying party(ies) attached? Yes 🖌 No	
3. Nature of conveyance:	
✓ Assignment Merger	
Security Agreement Change of Name	Street Address: <u>No. 8, Li-Hsin Road 6</u>
Other	Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77
	City: <u>Hsin-Chu</u> State:Zip: <u>300-77</u>
Execution Date: <u>April 8, 2004</u>	Additional name(s) & address(es) attached? Yes 🖌 No
Application number(s) or patent number(s):	
If this document is being filed together with a new app	ication, the execution date of the application is:
A. Patent Application No.(s) 10/854061	B. Patent No.(s)
Additional numbers a	ttached? Yes No
5. Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
Name: Timothy F. Bliss	7. Total fee (37 CFR 3.41)\$40.00
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Street Address: <u>Haynes and Boone, LLP</u>	Authorized to be charged to deposit account 8. Deposit account number:
Street Address: Haynes and Boone, LLP 901 Main Street, Suite 3100 City: DallasState: TX_Zip: 75202	Authorized to be charged to deposit account 8. Deposit account number:
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5 - 5 - 6 - ¹⁹

PATENT REEL: 015387 FRAME: 0664

ASSIGNMENT

WHEREAS, we

(1)	Chi-Wen Liu	of	5F, No. 111, Minshiang St., Hsin-Chu ,Taiwan 300 Republic of China
(2)	Jung-Chih Tsao	of	5F, No. 111, Minshiang St., Hsin-Chu, Taiwan 300 Republic of China
(3)	Shih-Tzung Chang	of	5F, No. 111, Minshiang St., Hsin-Chu, Taiwan 300 Republic of China
(4)	Ying-Lang Wang	of	5F, No. 111, Minshiang St., Hsin-Chu, Taiwan 300 Republic of China
(5)	Kei-Wei Chen	of	1F, No. 224, Yung-Li Rd., Yung-ho, Taipei, Taiwan Republic of China 234

have invented certain improvements in

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METAL-FILLED OPENINGS FOR SUBMICRON DEVICES AND METHODS OF MANUFACTURE THEREOF

for which we have executed an application for Letters Patent of the United States of America, of even date herewith; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States

R-48741_1.DOC

PATENT REEL: 015387 FRAME: 0665 of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

First Inventor Name: Residence Address:

Dated: 4/8/2004

Dated:

Second Inventor Name:

Dated: 4/8/2054

Dated:

Chi-Wen Liu 5F, No. 111, Minshiang St., Hsin-Chu, Taiwan 300 Republic of China

Chi-wen Li Chi-Wen Liu (Inventor Signature)

Witness Signature Witness Name:____

Jung-Chih Tsao 5F, No. 111, Minshiang St., Hsin-Chu, Taiwan 300 **Republic of China**

Jung-Chih Tsao (Inventor Signature)

Witness Signature Witness Name:

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2

PATENT REEL: 015387 FRAME: 0666 Patent / Docket No.: 24061.23/TSMC2002-0898 Customer No. 27683

Shih-Tzung Chang Third Inventor Name: 5F, No. 111, Minshiang St., Hsin-Chu, Taiwan 300 Republic of China Shih - TEUN & Chart Shih-Tzung Chang (Inventor Signature) Dated: Witness Signature Witness Name: Fourth Inventor Name: Ying-Lang Wang 5F, No. 111, Minshiang St., Hsin-Chu, Taiwan 300 Republic of China Ying - Lang Warn Ying-Lang Wang (Inventor Signature) Dated: ______ 200 4 Dated: Witness Signature Witness Name: . Fifth Inventor Name: Kei-Wei Chen 1F, No. 224, Yung-Li Rd. Yung-ho, Taipei, Taiwan 234 Republic of China Dated: 4/8/2004 Wei Chen ei Chen (Inventor Signature) Dated: Witness Signature Witness Name: R-48741_1.DOC 3 PATENT REEL: 015387 FRAME: 0667

RECORDED: 05/26/2004